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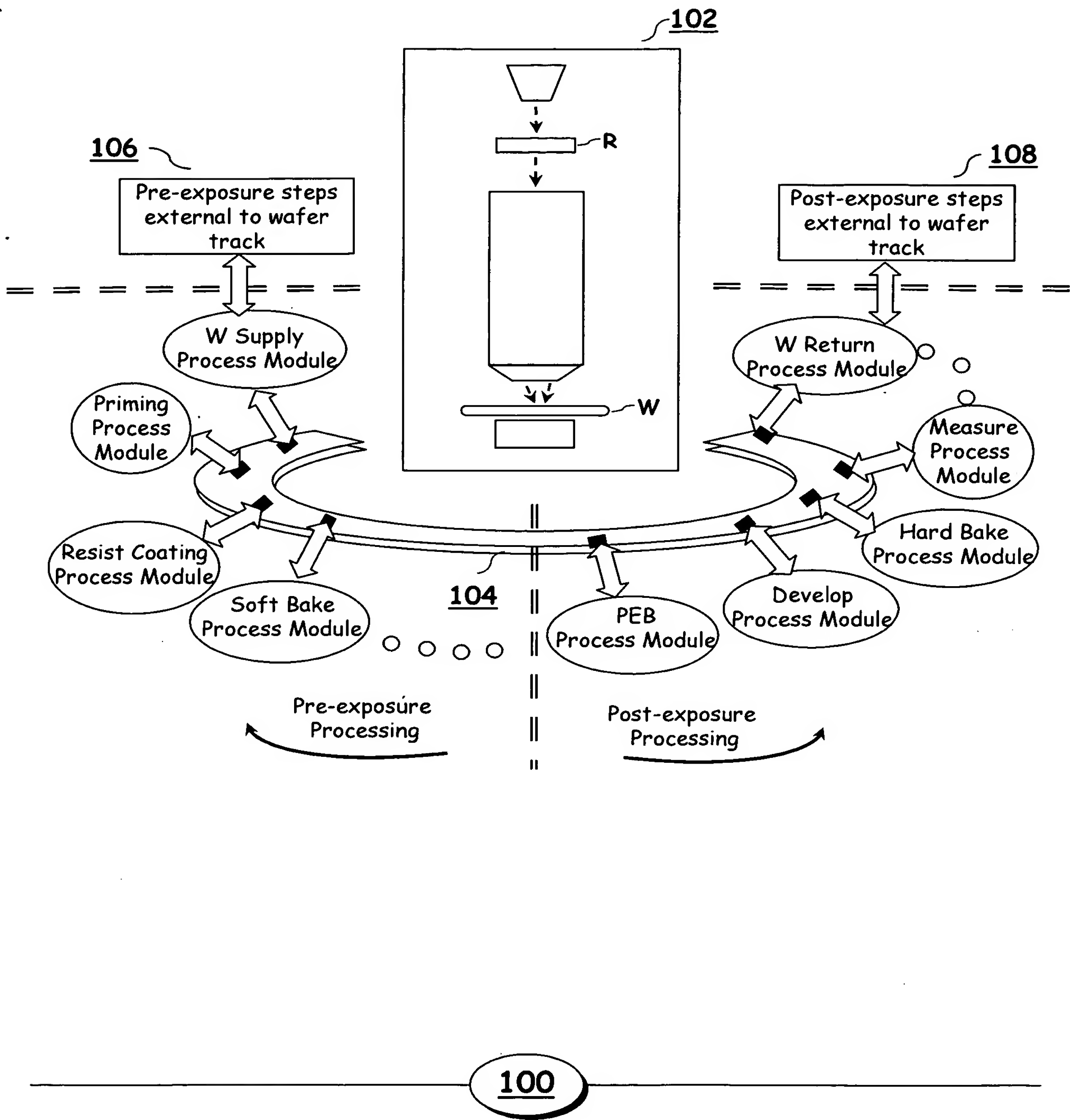
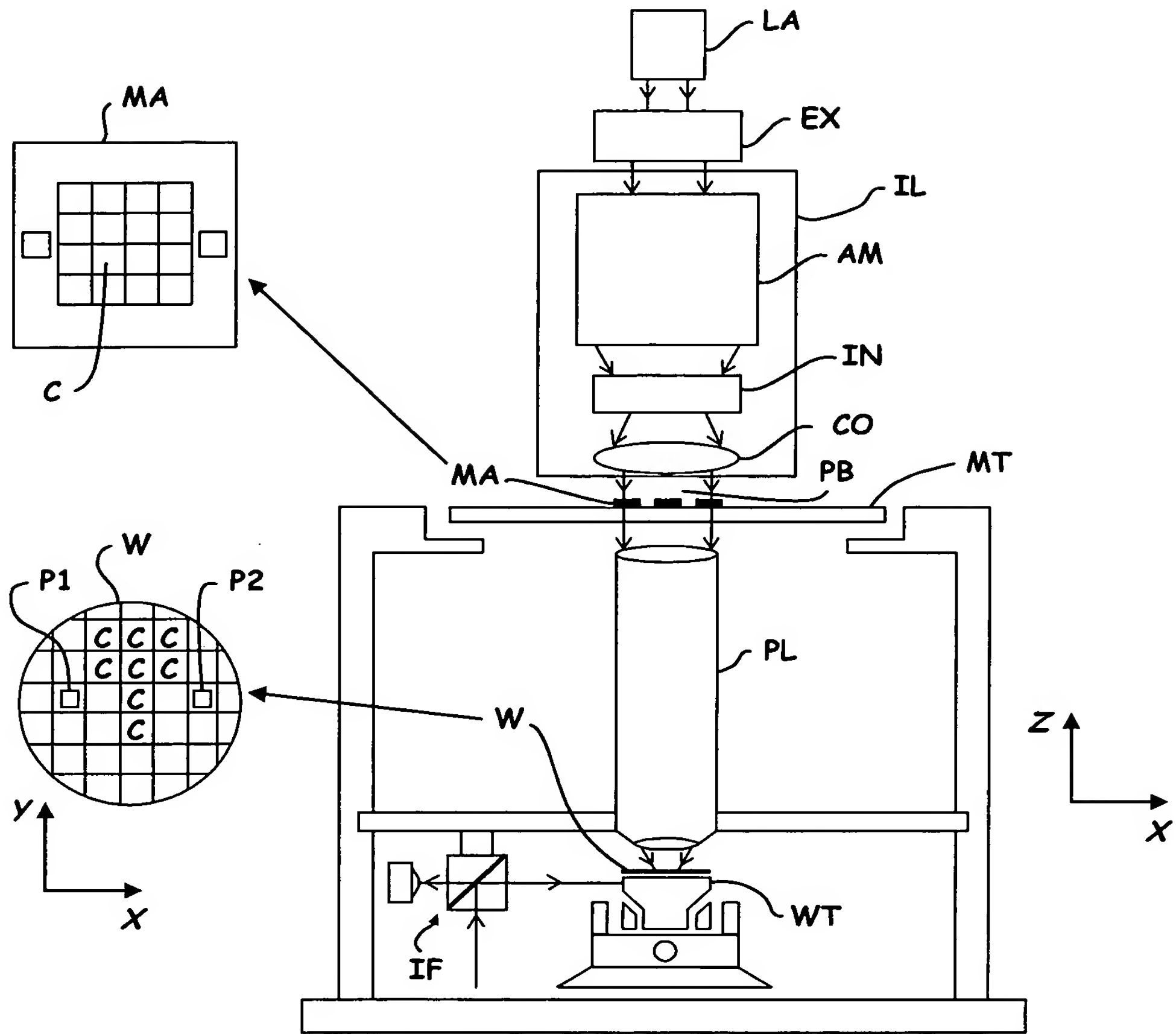
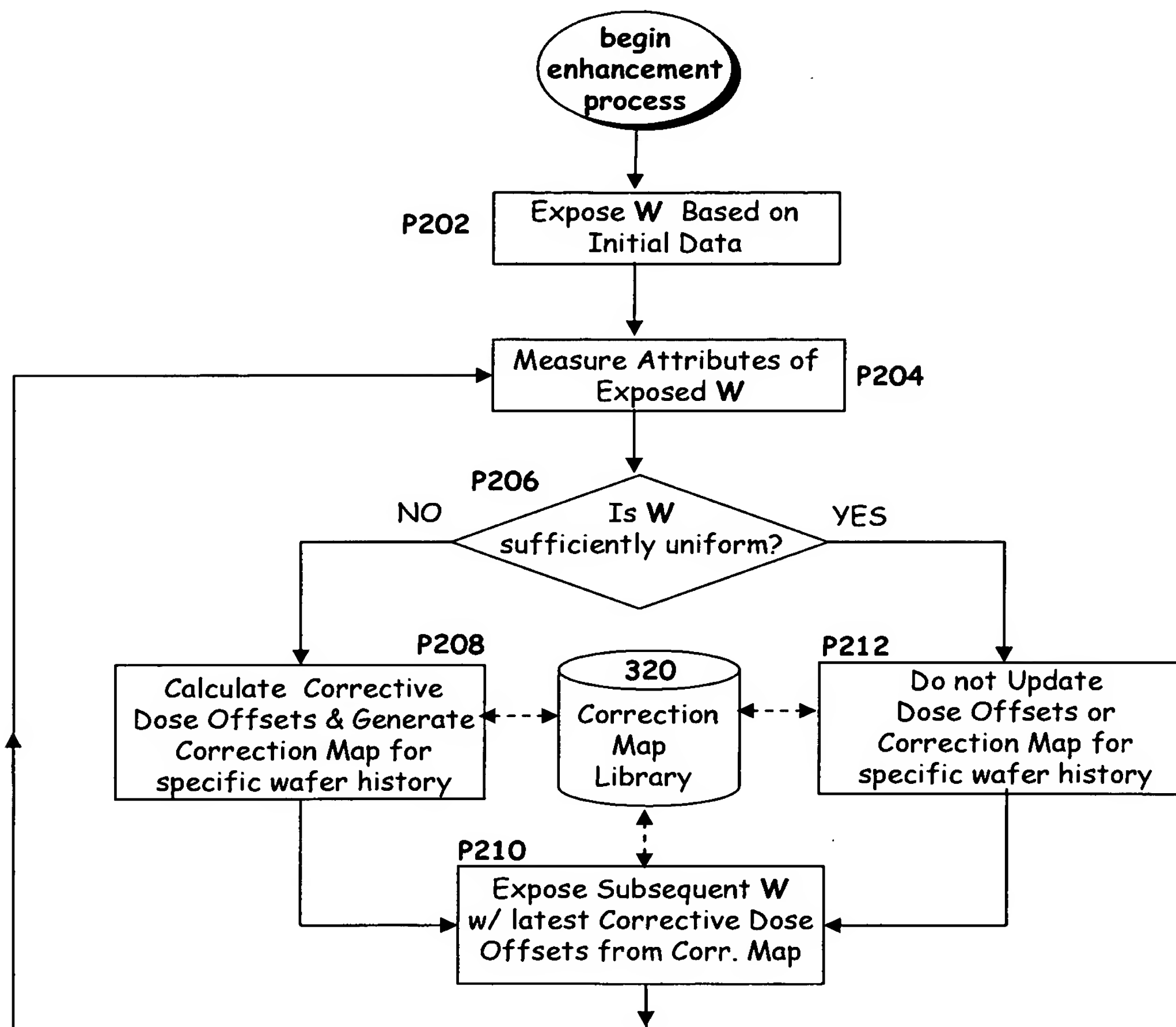


FIG. 1A



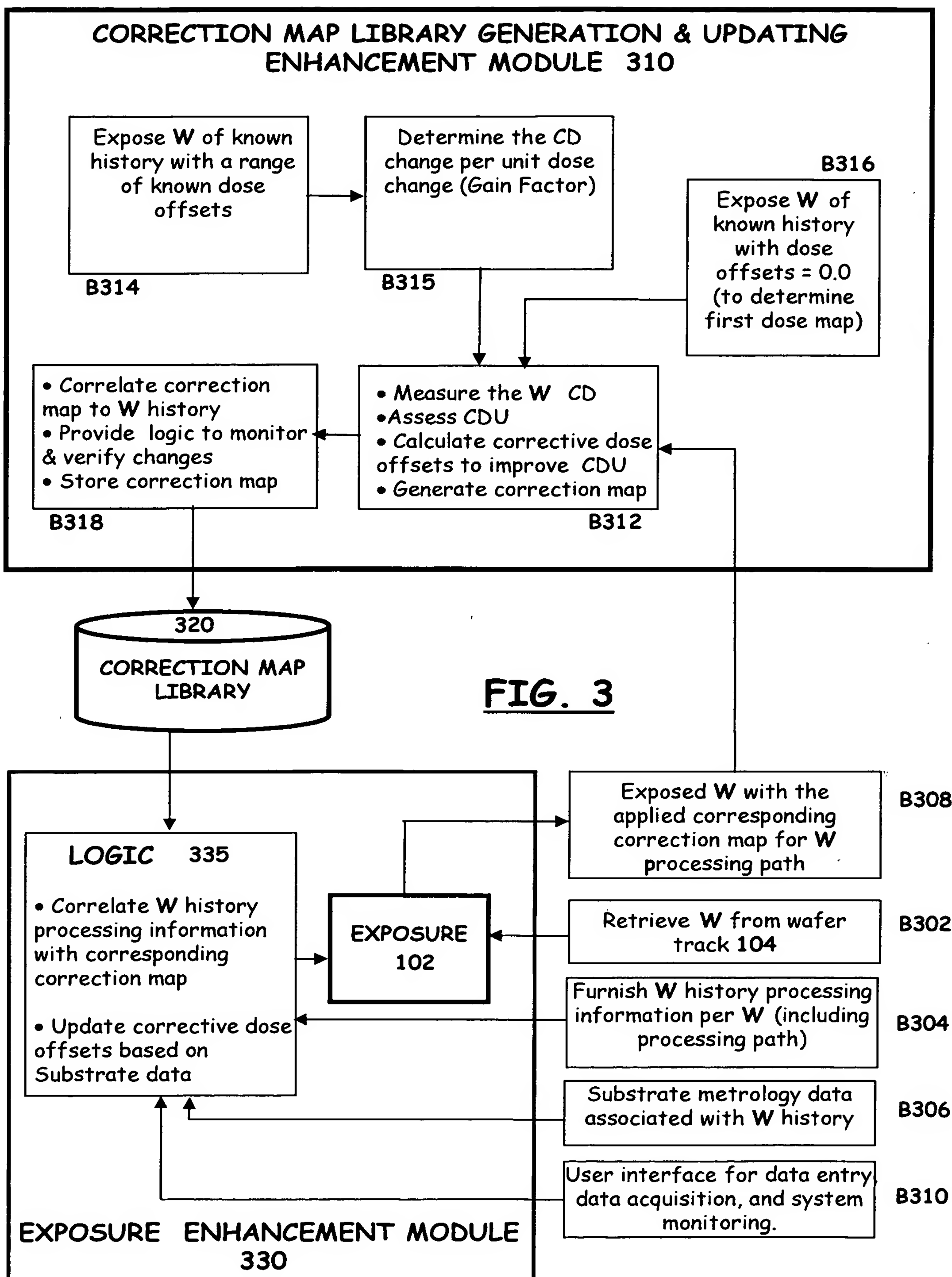
102

FIG. 1B



200

FIG. 2



Examples Pre Exposure Substrate Metrology Data (B306)

Resist thickness

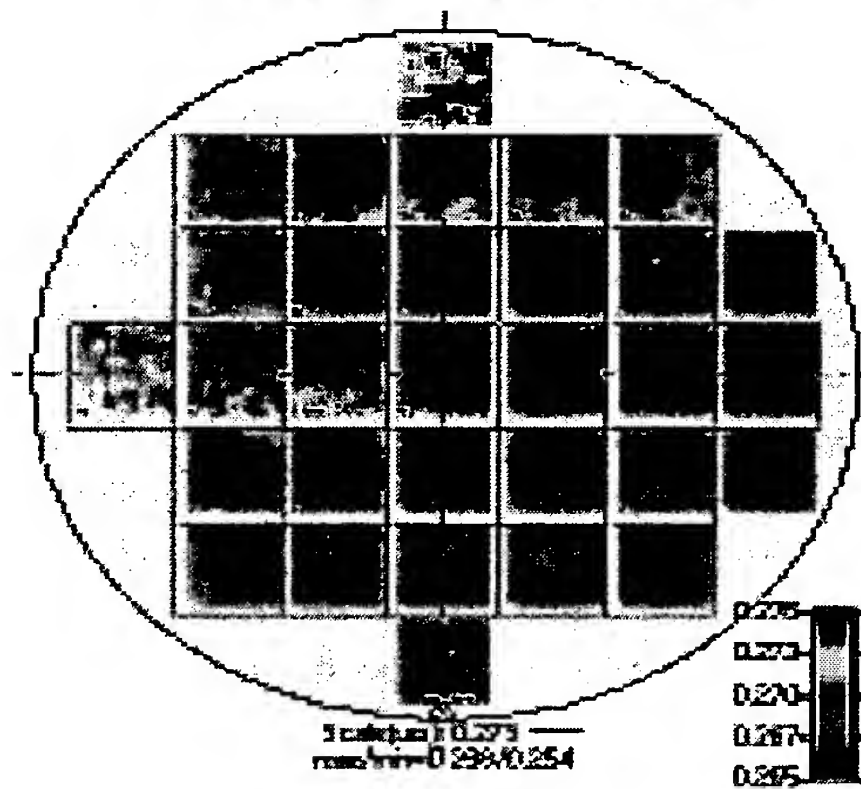


FIG. 4A

BARC Thickness

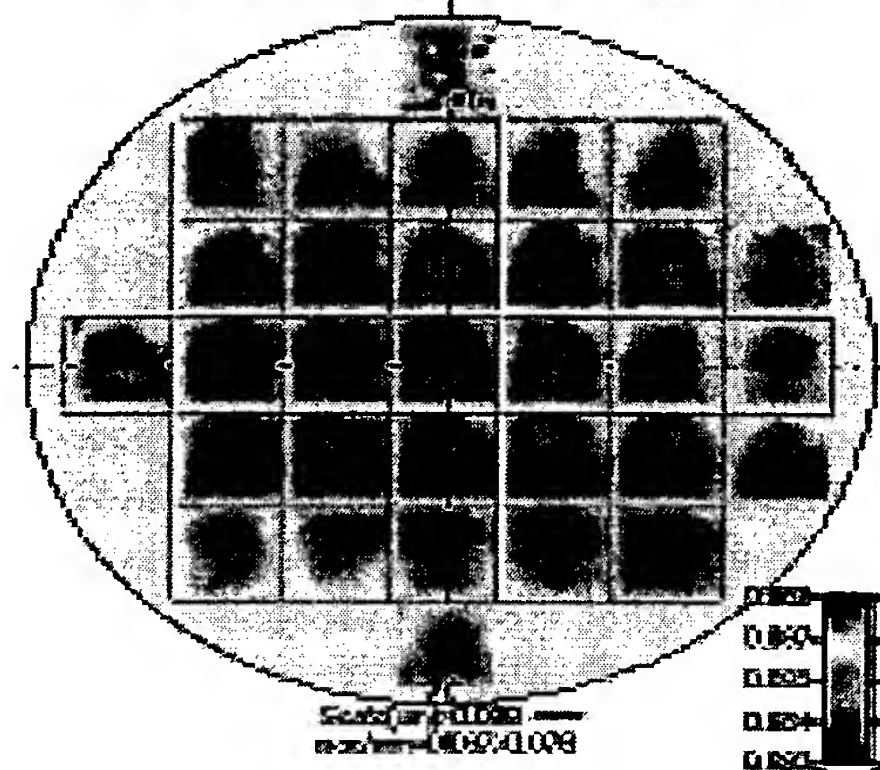


FIG. 4B

Example Wafer Dose Layout & Range (B314)

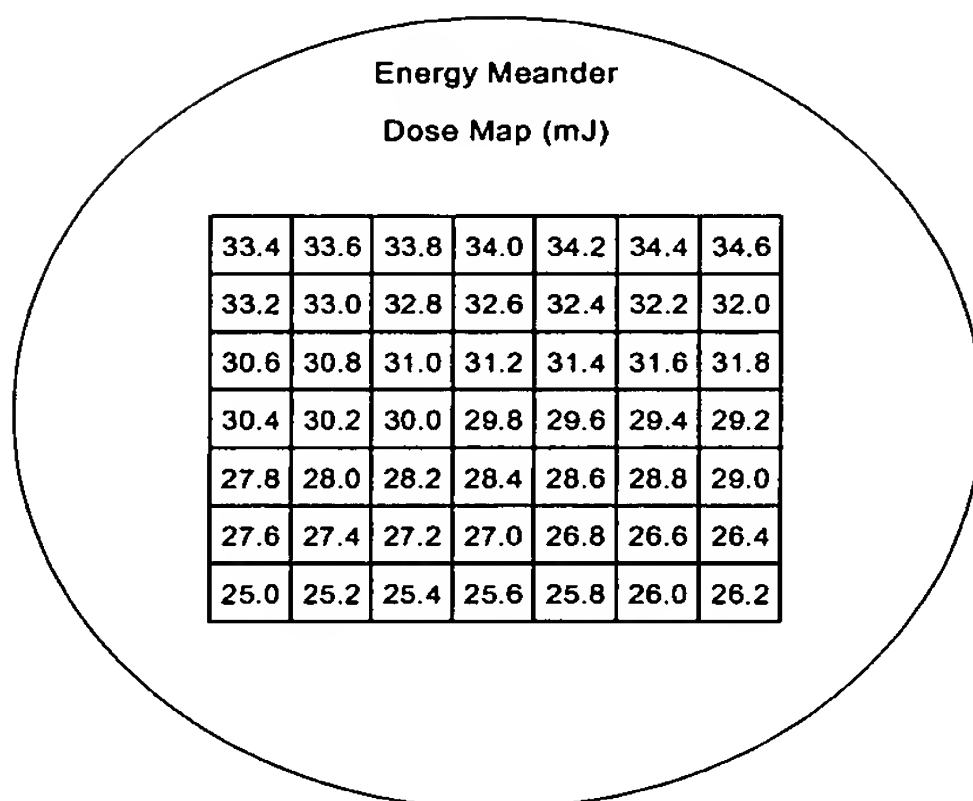


FIG. 4C

Example CD Change per Unit Dose (B315)

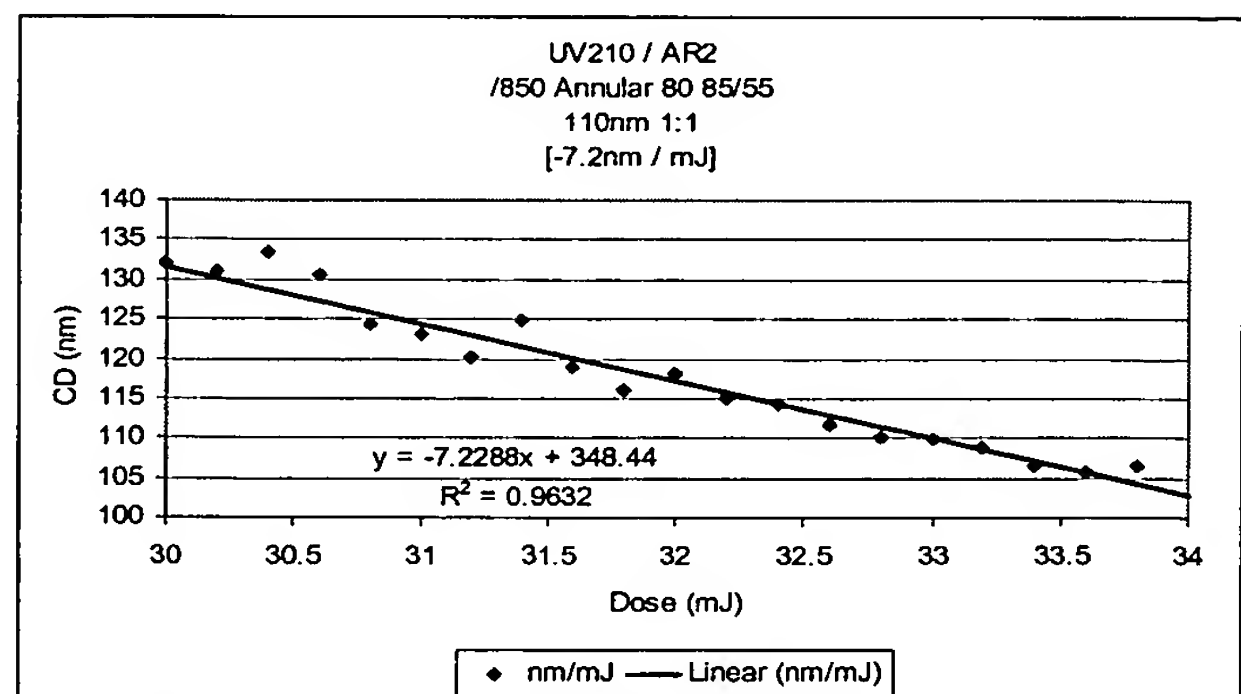


FIG. 4D

**Example Initial Dose Map:
 Dose Offset = 0 (B316)**

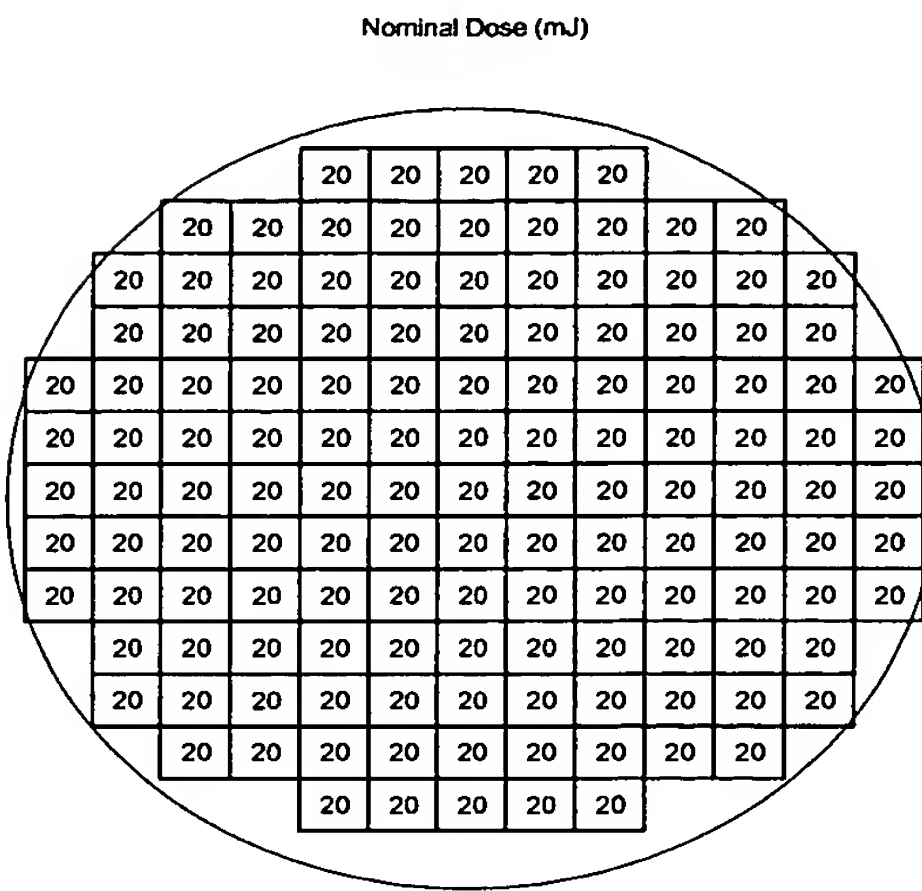


FIG. 4E

**Example CD Results:
 with Dose Offset = 0 (B312)**

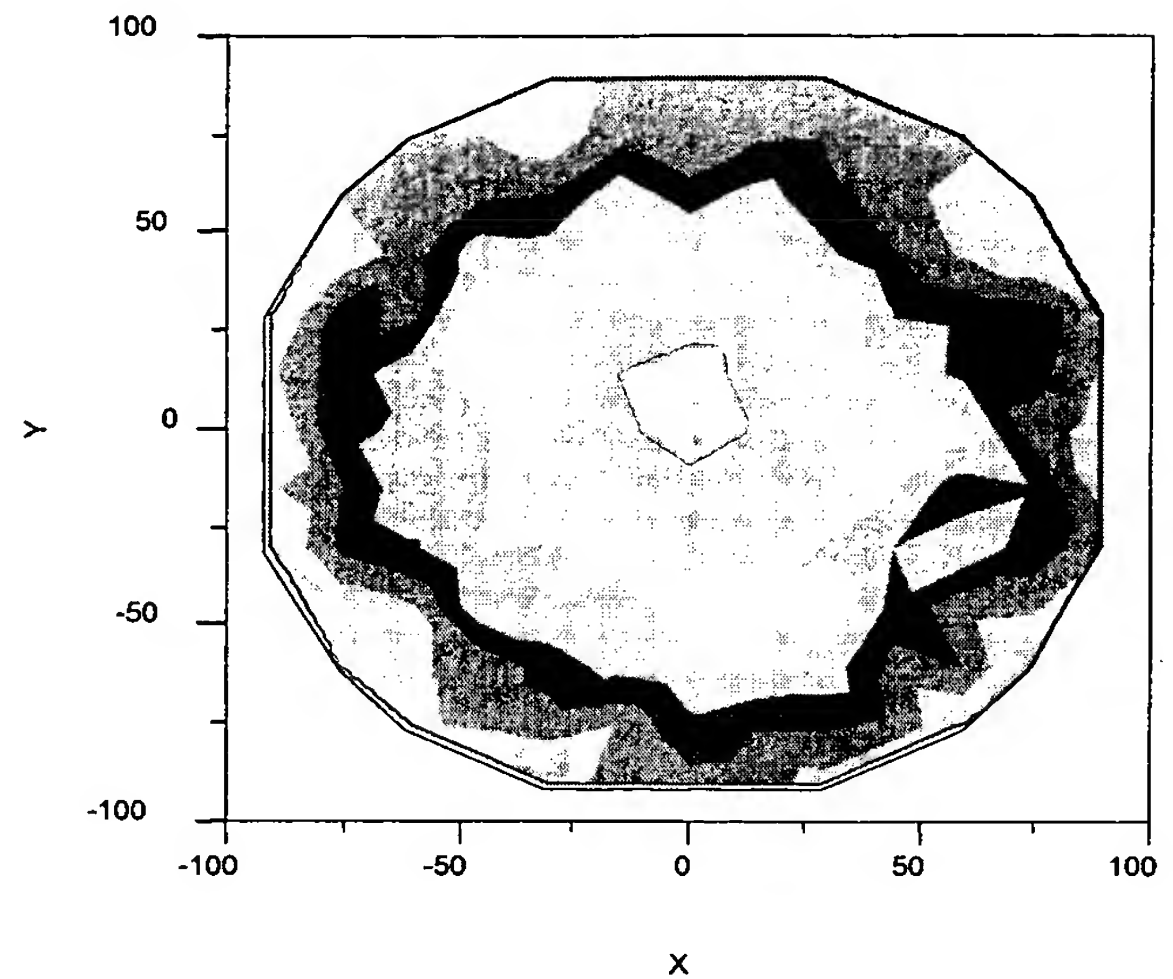


FIG. 4F

**Example Wafer Dose
 Layout with Dose Offset (B308)**

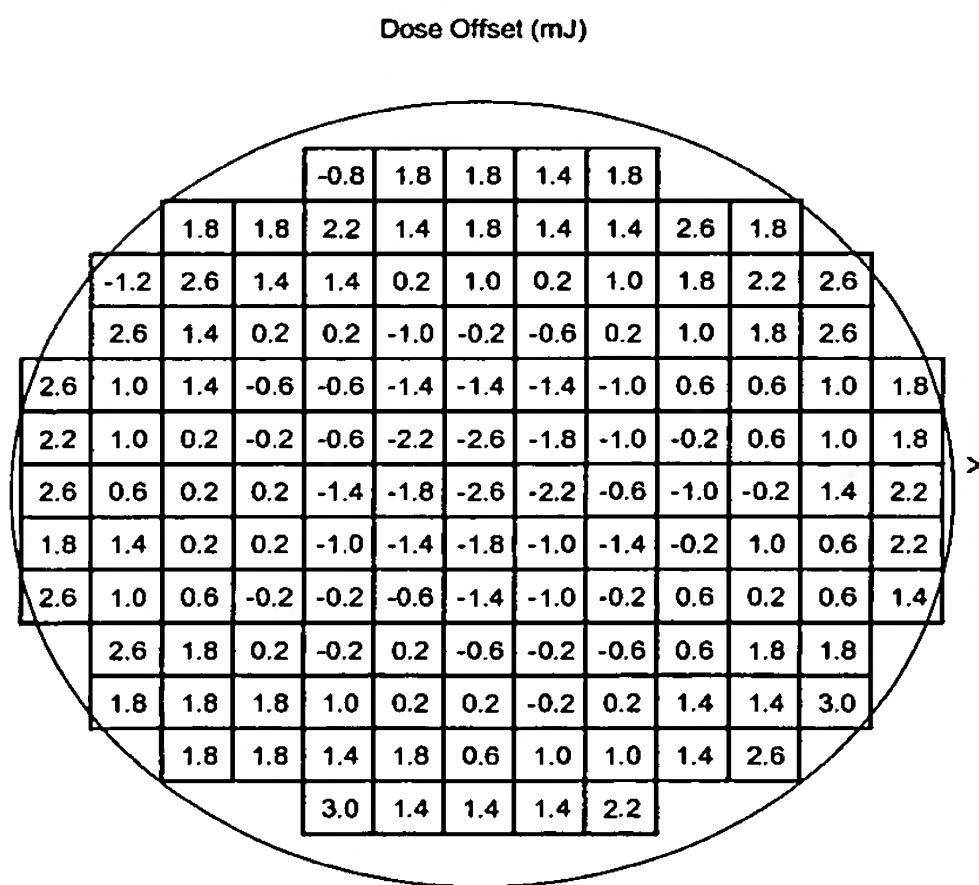


FIG. 4G

**Example CD Results:
 with Applied Dose Offset (B312)**

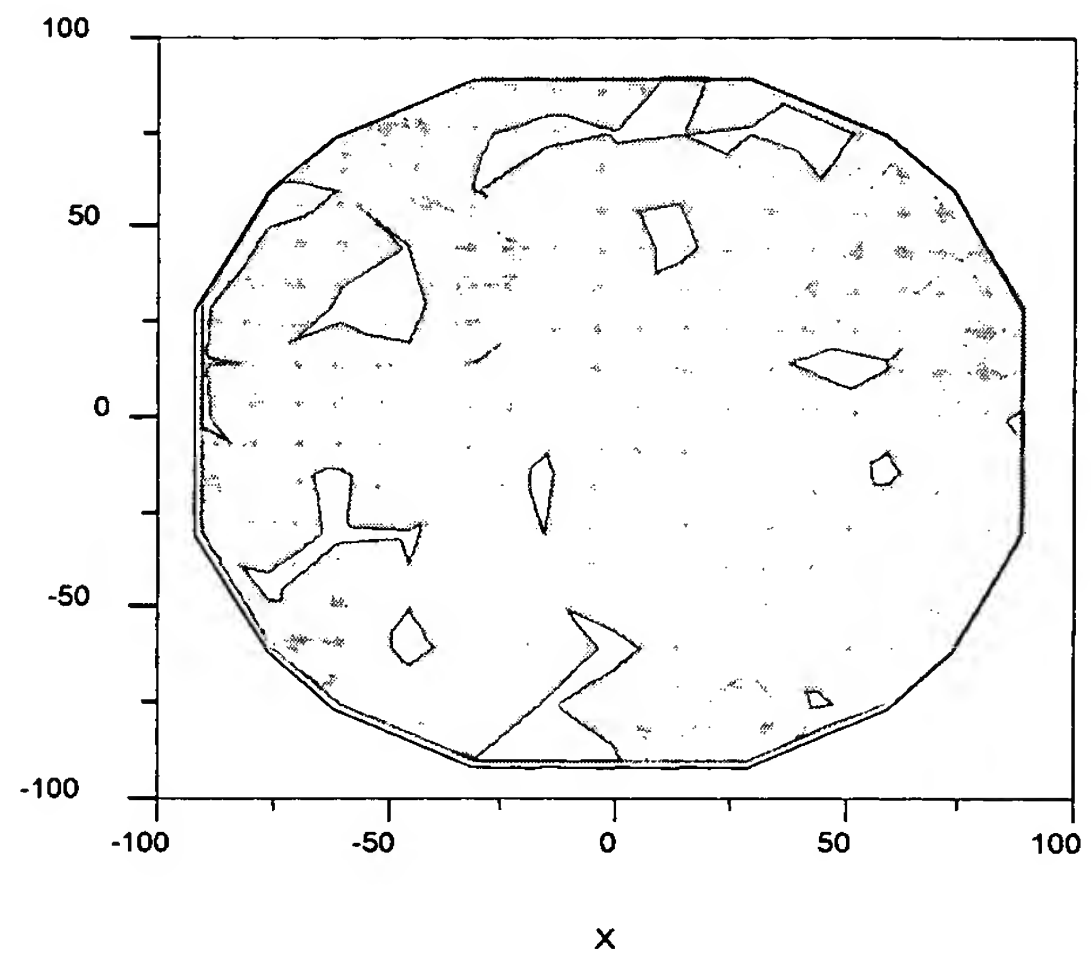


FIG. 4H